



Description

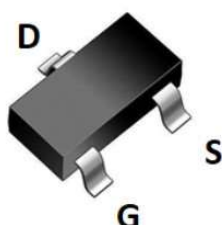
JMT N-channel Enhancement Mode Power MOSFET

Features

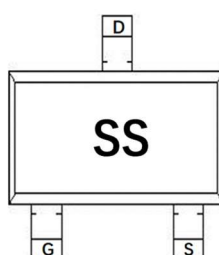
- $V_{DS}=50V$, $I_D=0.22A$
 $R_{DS(ON)} < 3\Omega$ @ $V_{GS} = 10V$
 $R_{DS(ON)} < 4\Omega$ @ $V_{GS} = 4.5V$
- High Power and Current Handling Capability
- Lead Free Product is Acquired
- Surface Mount Package

Application

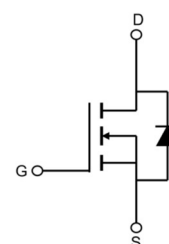
- Battery Protection
- Load Switch
- Power Management



SOT-23 top view



Marking and pin Assignment



Schematic diagram

Package Marking and Ordering Information

Device Marking	Device	OUTLINE	Device Package	Reel Size	Reel (PCS)	Per Carton (PCS)
SS	JMTL138A	TAPING	SOT-23	13inch	4000	40000

Absolute Maximum Ratings ($T_A=25^\circ C$ unless otherwise specified)

Symbol	Parameter		Max.	Units
V_{DSS}	Drain-Source Voltage		50	V
V_{GSS}	Gate-Source Voltage		± 20	V
I_D	Continuous Drain Current	$T_A = 25^\circ C$	220	mA
		$T_A = 100^\circ C$	143	
I_{DM}	Pulsed Drain Current ^{note1}		880	mA
P_D	Power Dissipation	$T_A = 25^\circ C$	0.3	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient		417	$^\circ C/W$
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +150	$^\circ C$



Electrical Characteristics (T_J=25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	50	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =50V, V _{GS} =0V,	-	-	1	μA
I _{GSS}	Gate to Body Leakage Current	V _{DS} =0V, V _{GS} = ±20V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	0.8	1	1.45	V
R _{DS(on)}	Static Drain-Source on-Resistance note2	V _{GS} =10V, I _D =0.5A	-	1.5	3	Ω
		V _{GS} =4.5V, I _D =0.2A	-	1.8	4	
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =25V, V _{GS} =0V, f=1.0MHz	-	40	-	pF
C _{oss}	Output Capacitance		-	12	-	pF
C _{rss}	Reverse Transfer Capacitance		-	3.5	-	pF
Q _g	Total Gate Charge	V _{DS} =25V, I _D =0.2A, V _{GS} =10V	-	3	-	nC
Q _{gs}	Gate-Source Charge		-	0.6	-	nC
Q _{gd}	Gate-Drain(“Miller”) Charge		-	0.1	-	nC
Switching Characteristics						
t _{d(on)}	Turn-on Delay Time	V _{DD} =20V, I _D =0.2A,	-	-	20	ns
t _{d(off)}	Turn-off Delay Time	R _{GEN} =10Ω, V _{GS} =10V,	-	-	20	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	0.22	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	0.88	A
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0V, I _S =0.2A	-	-	1.2	V

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. Pulse Test: Pulse Width≤300μs, Duty Cycle≤2%

Typical Performance Characteristics

Figure1: Output Characteristics

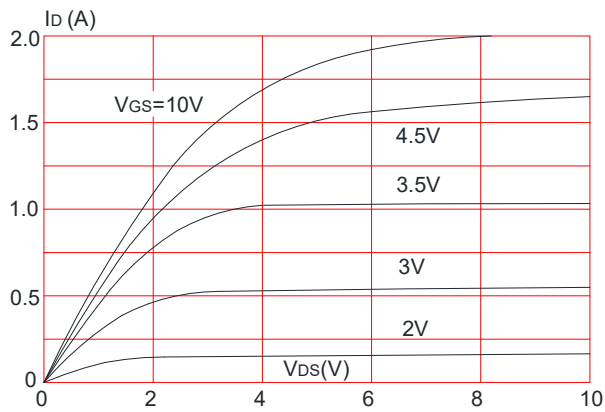


Figure 2: Typical Transfer Characteristics

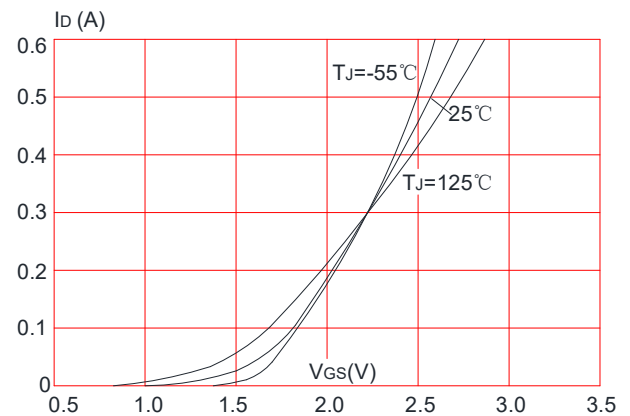


Figure 3: On-resistance vs. Drain Current

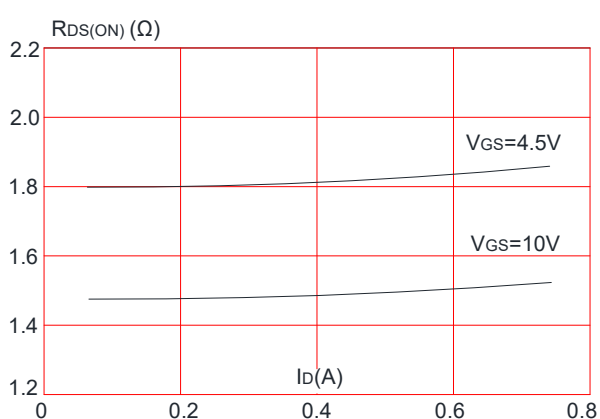


Figure 4: Body Diode Characteristics

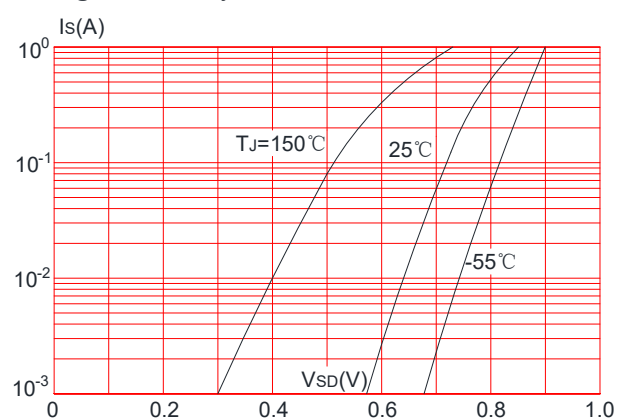


Figure 5: Gate Charge Characteristics

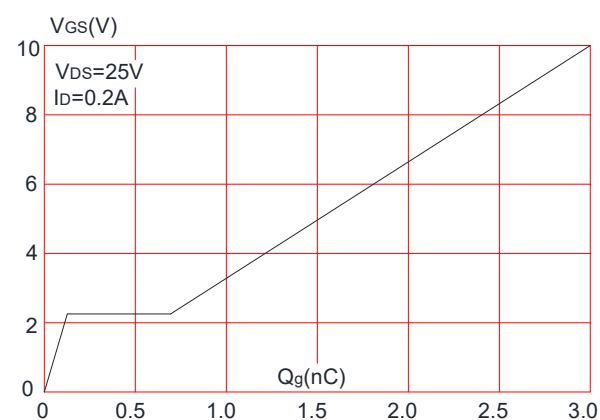


Figure 6: Capacitance Characteristics

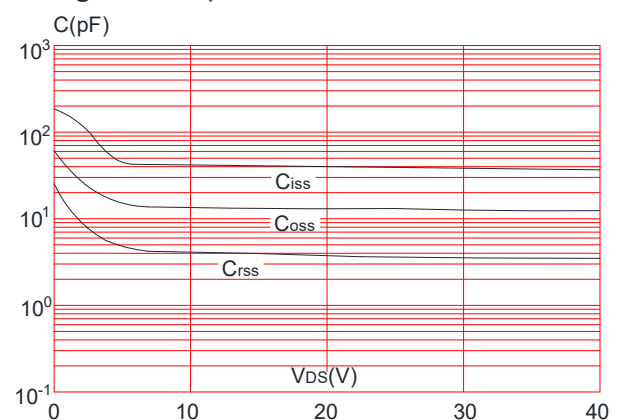


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

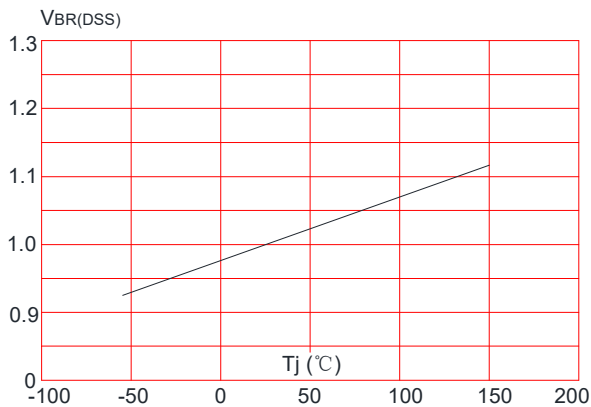


Figure 8: Normalized on Resistance vs. Junction Temperature

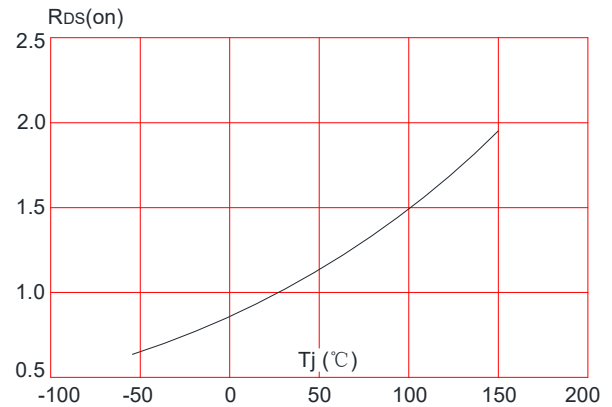


Figure 9: Maximum Safe Operating Area

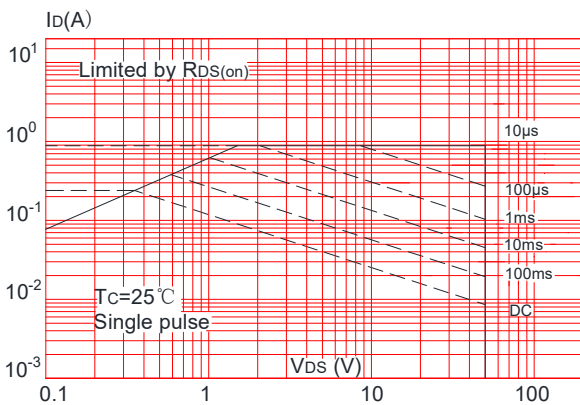


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

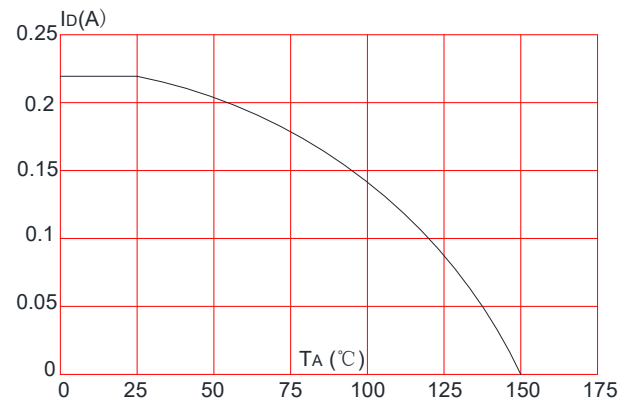
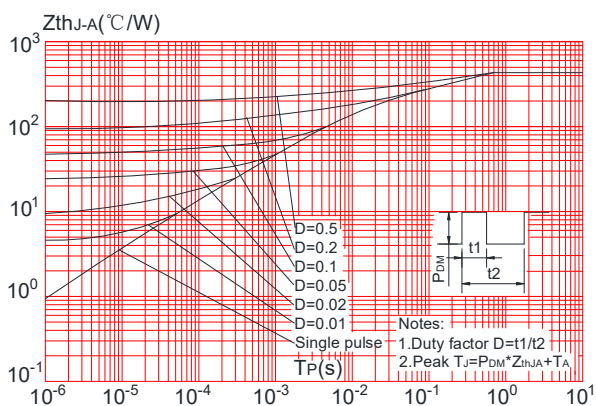


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



Test Circuit

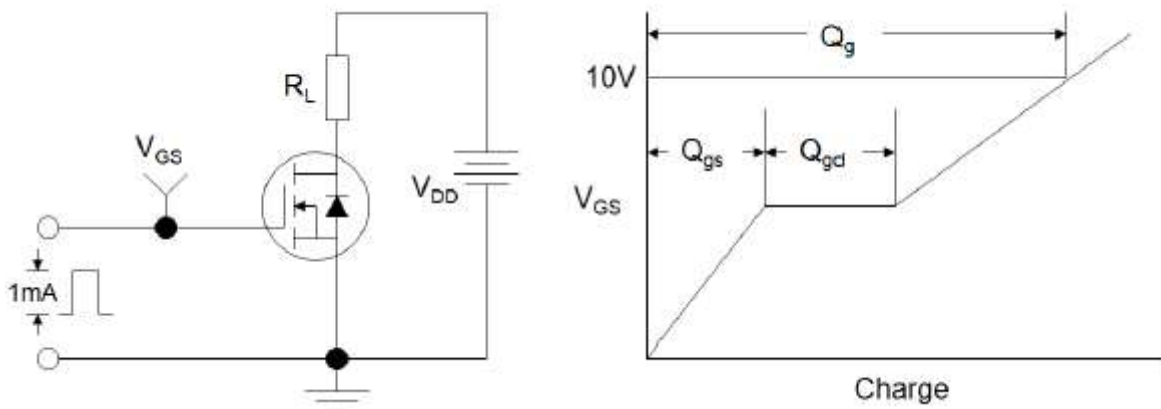


Figure1:Gate Charge Test Circuit & Waveform

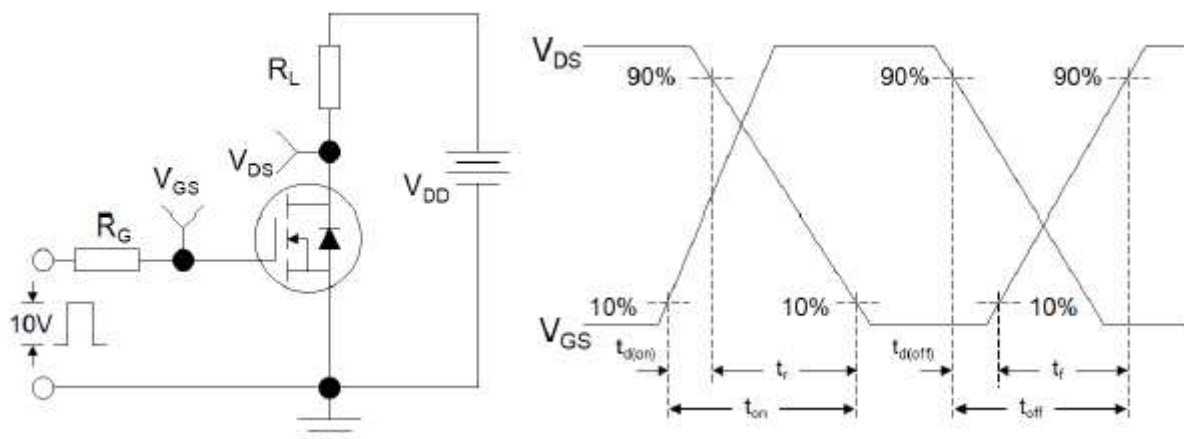


Figure 2: Resistive Switching Test Circuit & Waveforms

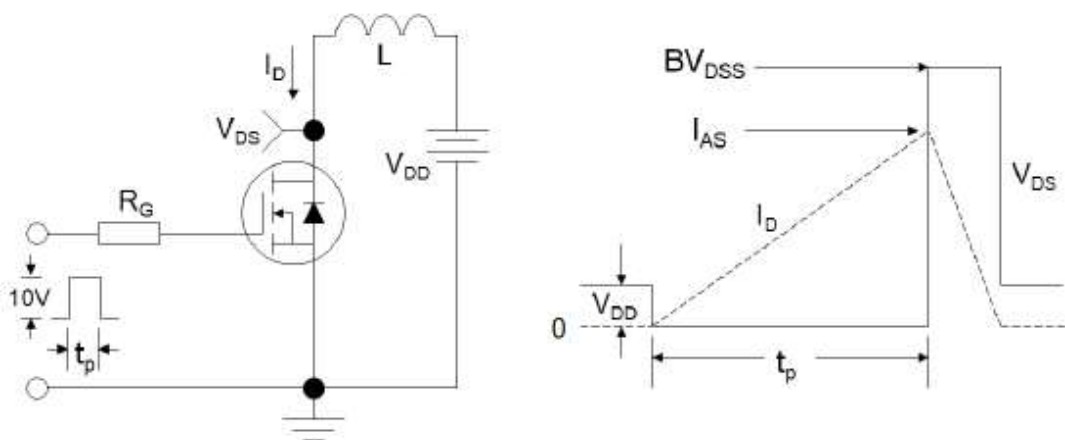


Figure 3:Unclamped Inductive Switching Test Circuit & Waveforms

Technical drawing of a rectangular box with dimensions A, B, C, D, E, F, G, H, and I. The drawing shows the front view (left) and the side view (right). The front view shows a rectangular box with a central opening of width C and height E. The total width is B, and the total height is A. The side view shows the box with a total width of G, a height of H, and a depth of F. The side view also shows the internal structure of the box, including the central opening and the side walls.

SOT-23

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.30	2.40	2.50	0.091	0.095	0.098
B	2.80	2.90	3.00	0.110	0.114	0.118
C	1.90 REF			0.075 REF		
D	0.35	0.40	0.45	0.014	0.016	0.018
E	1.20	1.30	1.40	0.047	0.051	0.055
F	0.90	1.00	1.10	0.035	0.039	0.043
G		0.10	0.15		0.004	0.006
H	0.20			0.008		
I	0		0.10	0		0.004

Ref.	Dimensions	
	Millimeters	Inches
A0	3.15 ± 0.3	0.124 ± 0.012
B0	2.77 ± 0.3	0.109 ± 0.012
C	178	7.0
D0	1.50±0.1	0.059 ± 0.004
E	1.75 ± 0.2	0.069 ± 0.008
E1	13.3±0.3	0.524± 0.012
F	3.5 ± 0.2	0.138 ± 0.008
P0	4.00 ± 0.2	0.157 ± 0.008
P1	4.00 ± 0.2	0.157 ± 0.008
P2	2.00 ± 0.2	0.079 ± 0.008
W	8.00 ± 0.2	0.315 ± 0.008
W1	11.5±1.0	0.453 ± 0.039



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